

# MBRA210LT3G, NRVBA210LT3G

## Surface Mount Schottky Power Rectifier

### SMA Power Surface Mount Package

This device employs the Schottky Barrier principle in a metal-to-silicon power rectifier. Features epitaxial construction with oxide passivation and metal overlay contact. Ideally suited for low voltage, high frequency switching power supplies; free wheeling diodes and polarity protection diodes. Typical applications are AC-DC and DC-DC converters, reverse battery protection, and "Oring" of multiple supply voltages and any other application where performance and size are critical.

#### Features

- Ultra Low  $V_F$
- 1st in the Market Place with a 10  $V_R$  Schottky Rectifier
- Compact Package with J-Bend Leads Ideal for Automated Handling
- Highly Stable Oxide Passivated Junction
- Guardring for Over-Voltage Protection
- Optimized for Low Forward Voltage
- AEC-Q101 Qualified and PPAP Capable
- NRVBA Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements
- All Packages are Pb-Free\*

#### Mechanical Characteristics:

- Case: Molded Epoxy
- Epoxy Meets UL 94 V-0 @ 0.125 in
- Weight: 70 mg (Approximately)
- Finish: All External Surfaces Corrosion Resistant and Terminal Leads are Readily Solderable
- Lead and Mounting Surface Temperature for Soldering Purposes: 260°C Max. for 10 Seconds
- Polarity: Polarity Band Indicates Cathode Lead
- ESD Ratings:
  - ◆ Machine Model = C
  - ◆ Human Body Model = 3A



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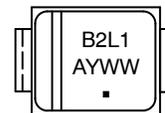
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**SCHOTTKY BARRIER  
RECTIFIER  
2 AMPERES  
10 VOLTS**



**SMA  
CASE 403D  
PLASTIC**

#### MARKING DIAGRAM



B2L1 = Specific Device Code  
A = Assembly Location  
Y = Year  
WW = Work Week  
▪ = Pb-Free Package

#### ORDERING INFORMATION

Device	Package	Shipping†
MBRA210LT3G	SMA (Pb-Free)	5,000/Tape & Reel
NRVBA210LT3G	SMA (Pb-Free)	5,000/Tape & Reel

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

\*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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## MAXIMUM RATINGS

Rating	Symbol	Value	Unit
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage	$V_{RRM}$ $V_{RWM}$ $V_R$	10	V
Average Rectified Forward Current (At Rated $V_R$ , $T_L = 110^\circ\text{C}$ )	$I_O$	2.0	A
Non-Repetitive Peak Surge Current (Surge Applied at Rated Load Conditions Halfwave, Single Phase, 60 Hz)	$I_{FSM}$	160	A
Storage/Operating Case Temperature Operating Junction Temperature	$T_{stg}, T_C$ $T_J$	-55 to +125	$^\circ\text{C}$
Voltage Rate of Change (Rated $V_R$ , $T_J = 25^\circ\text{C}$ )	dv/dt	10,000	V/ $\mu\text{s}$

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

## THERMAL CHARACTERISTICS

Characteristic	Symbol	Min Pad	1 Inch Pad	Unit
Thermal Resistance, Junction-to-Lead Thermal Resistance, Junction-to-Ambient	$R_{\theta JL}$ $R_{\theta JA}$	22 150	15 81	$^\circ\text{C}/\text{W}$

## ELECTRICAL CHARACTERISTICS

Maximum Instantaneous Forward Voltage (Note 1)  ( $I_F = 0.1\text{ A}$ ) ( $I_F = 1.0\text{ A}$ ) ( $I_F = 2.0\text{ A}$ )	$V_F$	$T_J = 25^\circ\text{C}$	$T_J = 100^\circ\text{C}$	V
		0.260	0.15	
		0.325	0.23	
Maximum Instantaneous Reverse Current  ( $V_R = 5.0\text{ V}$ ) ( $V_R = 10\text{ V}$ )	$I_R$	$T_J = 25^\circ\text{C}$	$T_J = 100^\circ\text{C}$	mA
		0.25	40	
		0.70	60	

1. Pulse Test: Pulse Width  $\leq 250\ \mu\text{s}$ , Duty Cycle  $\leq 2\%$ .

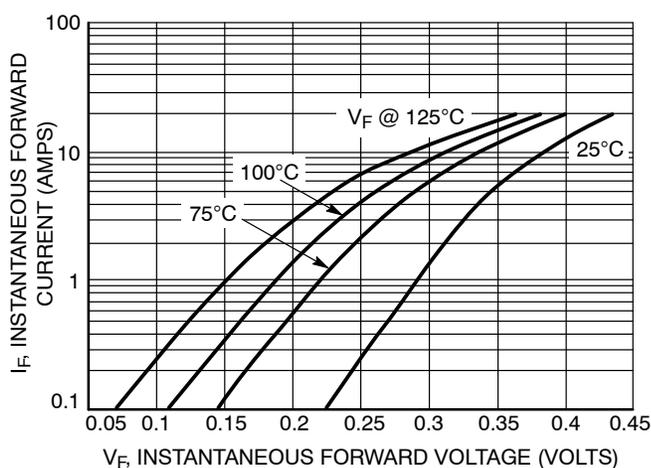


Figure 1. Typical Forward Voltage

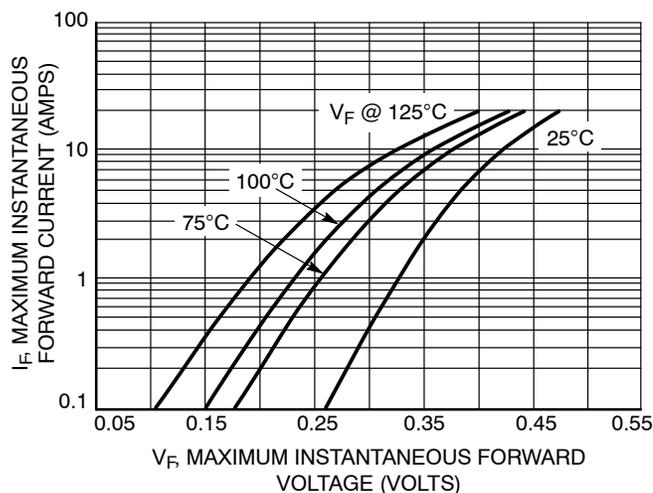
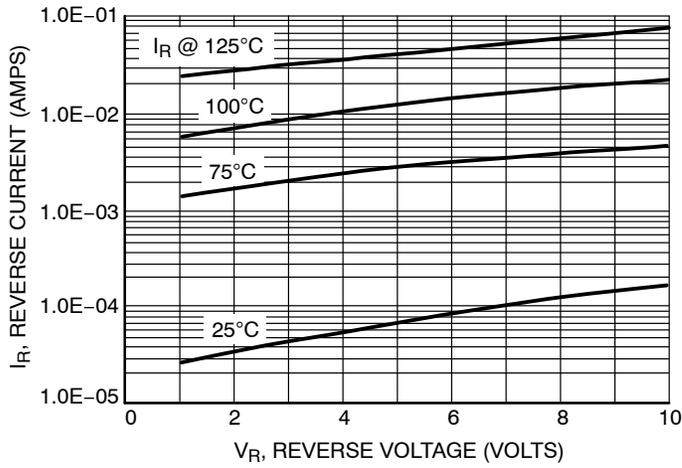
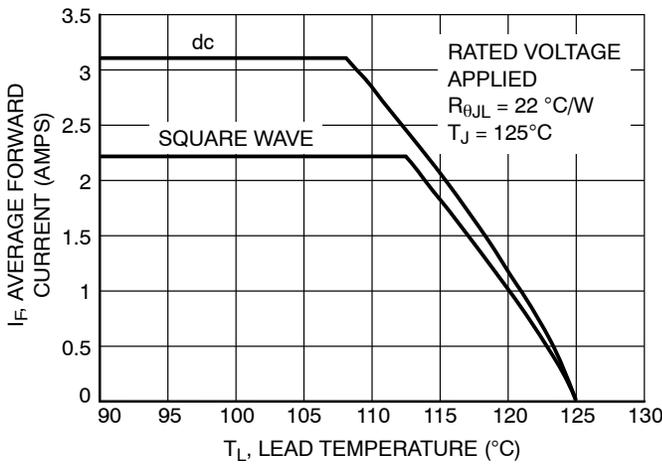


Figure 2. Maximum Forward Voltage

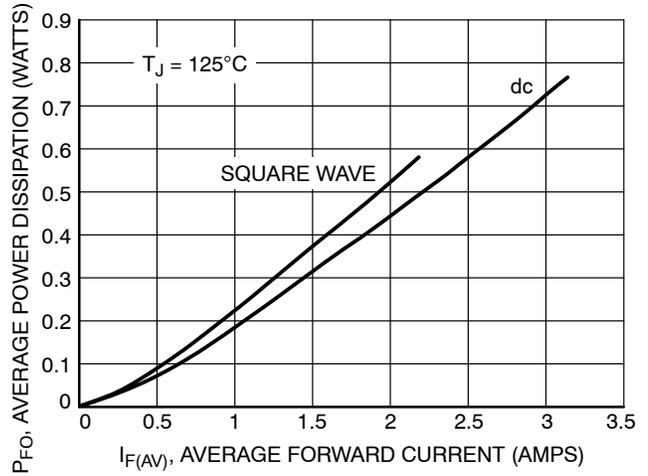
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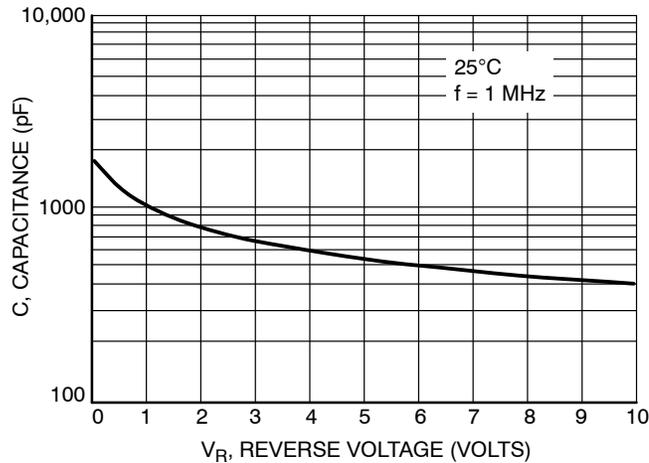
**Figure 3. Typical Reverse Current**



**Figure 4. Current Derating - Junction to Lead**



**Figure 5. Forward Power Dissipation**



**Figure 6. Typical Capacitance**

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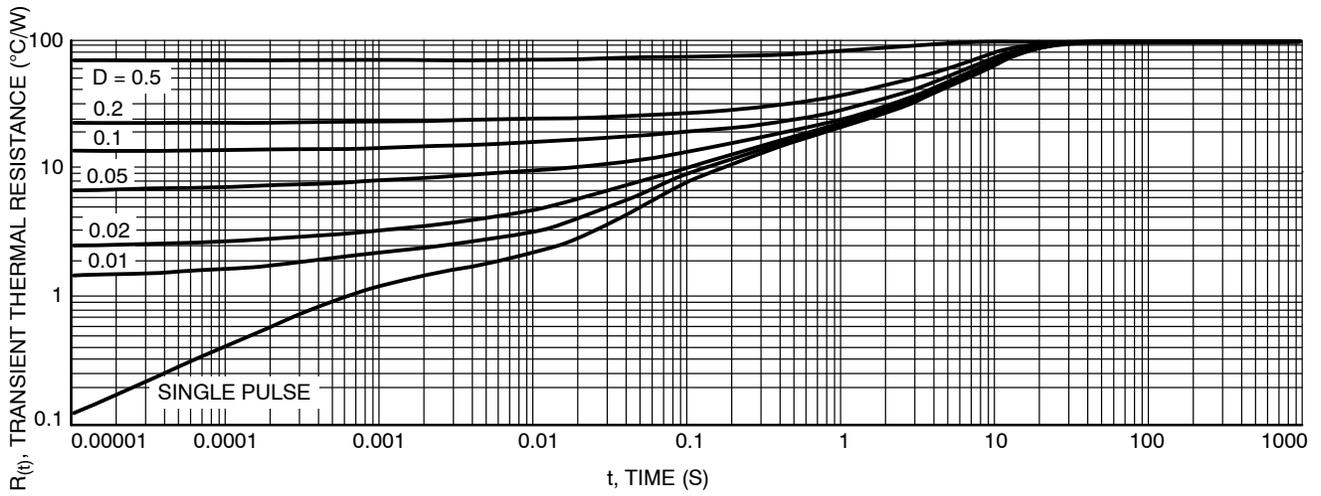


Figure 7. Thermal Response, Junction to Ambient (min pad)

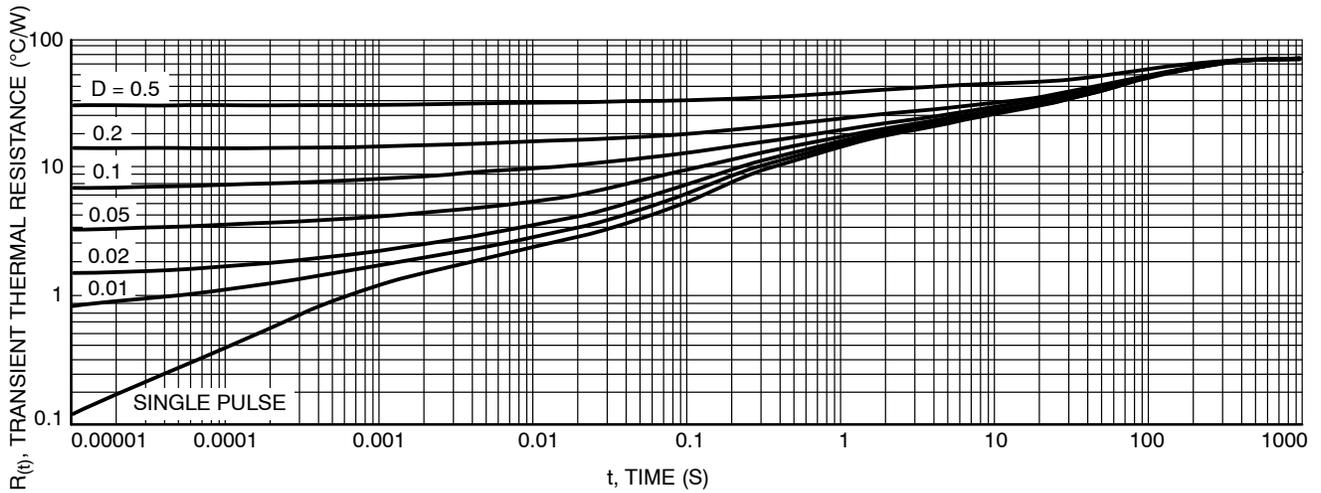
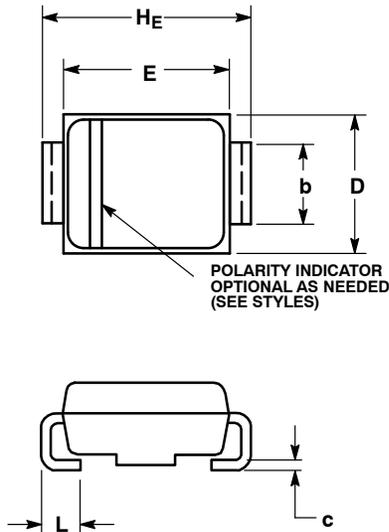


Figure 8. Thermal Response, Junction to Ambient (1 inch pad)

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## PACKAGE DIMENSIONS

SMA  
CASE 403D-02  
ISSUE F

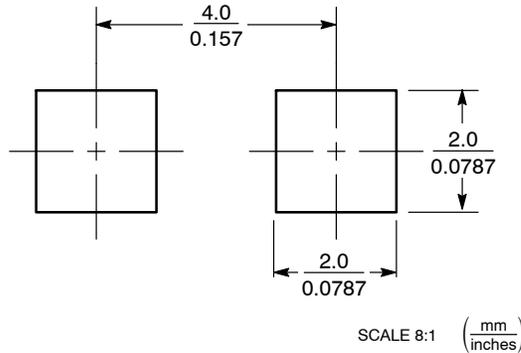


- NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
  2. CONTROLLING DIMENSION: INCH.
  3. 403D-01 OBSOLETE, NEW STANDARD IS 403D-02.

DIM	MILLIMETERS			INCHES		
	MIN	NOM	MAX	MIN	NOM	MAX
A	1.97	2.10	2.20	0.078	0.083	0.087
A1	0.05	0.10	0.15	0.002	0.004	0.006
b	1.27	1.45	1.63	0.050	0.057	0.064
c	0.15	0.28	0.41	0.006	0.011	0.016
D	2.29	2.60	2.92	0.090	0.103	0.115
E	4.06	4.32	4.57	0.160	0.170	0.180
HE	4.83	5.21	5.59	0.190	0.205	0.220
L	0.76	1.14	1.52	0.030	0.045	0.060

- STYLE 1:  
PIN 1. CATHODE (POLARITY BAND)  
2. ANODE

### SOLDERING FOOTPRINT\*



\*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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